

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/689998	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:08
S2	3796	ic near die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:32
S3	716	S2 and substrate and encapsulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:11
S4	1	S3 and "cured die attach film"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:11
S5	1	S3 and "cured die attach"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:11
S6	1	S2 and "cured die attach"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:12
S7	36	"cured die attach"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:12
S8	11048	(ic or "integrated circuit") near die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:32

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S9	30181	(ic or "integrated circuit") near package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:33
S10	3309	S8 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:33
S11	962000	mold	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:33
S12	583	S11 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:33
S13	26	S12 and heatsink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/06 16:33
S14	1	10/689998	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 10:17
S15	565	cured near die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 10:25
S16	1	cured near die near paste	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 10:40

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S17	0	cured near die near film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 10:25
S18	0	"cured die film"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 10:40
S19	814	microprocessor same die same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:14
S20	133	S19 and motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:14
S21	97	S20 and memory	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:16
S22	0	microprocessor with "double data rate memroy"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:17
S23	21	microprocessor with "double data rate memory"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:19
S24	21	(microprocessor micro\$processor) with "double data rate memory"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:21

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S25	65	motherboard and "double data rate memory"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:05
S26	25	S25 and ic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 11:59
S27	19100	ddr or "double data rate"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:06
S28	728	S27 and mother\$board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:17
S29	1540845	ic "integrated circuit"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:09
S30	14643	S28 adn S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:09
S31	431	S29 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:09
S32	199	S31 and microprocessor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:28

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S33	182	S27 same mother\$board	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:19
S34	27	S33 same S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:18
S35	324	microprocessor and motherboard and ("integrated circuit die" or (ic near die))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:29
S36	33	S35 and (ddr or "double data rate")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:42
S37	0	microprocessor with motherboard with (ddr "double data rate")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:43
S38	1557	microprocessor with motherboard	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:43
S39	88	S38 and (ddr or "double data rate")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/07 12:44
S40	13	("5641987" "5834839" "5872395" "5977626" "6124637" "6201301" "6534859").PN. OR ("6599779").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:06

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S41	16	("5371321" "5561085" "5608610" "5955789" "6043560" "6166435" "6177727" "6208526" "6225694" "6229404" "6243265" "6257904" "6282095" "6599779" "6630725" "6707168").PN. OR ("6819566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:07
S42	16	("5371321" "5561085" "5608610" "5955789" "6043560" "6166435" "6177727" "6208526" "6225694" "6229404" "6243265" "6257904" "6282095" "6599779" "6630725" "6707168").PN. OR ("6819566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:07
S43	16	("5371321" "5561085" "5608610" "5955789" "6043560" "6166435" "6177727" "6208526" "6225694" "6229404" "6243265" "6257904" "6282095" "6599779" "6630725" "6707168").PN. OR ("6819566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:09
S44	16	("5371321" "5561085" "5608610" "5955789" "6043560" "6166435" "6177727" "6208526" "6225694" "6229404" "6243265" "6257904" "6282095" "6599779" "6630725" "6707168").PN. OR ("6819566").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:09
S45	18	("4410905" "5067007" "5490324" "5640048" "5706579" "5717245" "5763939" "5789810" "5898219").PN. OR ("6225694").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:14
S46	8181	174/50.51.ccls. 257/704,693,698,697,783,778,678.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 11:31
S47	992	S46 and underfill	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:16

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S48	30	("20010008776" "5376588" "5696027" "5811317" "5866943" "5952726" "6015722" "6048753" "6053394" "6064113" "6111313" "6111756" "6114761" "6198635" "6201301" "6236568" "6250127" "6323066").PN. OR ("6472762").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 10:34
S49	18	S46 and overlayer	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 11:31
S50	3467	S46 and (encapsulat\$3 mold)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 11:43
S51	560	S50 and underfill	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 11:45
S52	79	("20020105092" "20020113324" "4772936" "4862322" "4948754" "4998159" "5082802" "5138434" "5147815" "5168345" "5216278" "5239198" "5246880" "5281151" "5289346" "5291062" "5311057" "5327008" "5327013" "5334857" "5355283" "5365409" "5376825" "5379191" "5384487" "5386341" "5399903" "5422163" "5424492" "5438224" "5440171" "5454160" "5483101" "5490040" "5490324" "5497397" "5498767" "5502289" "5506756" "5521435" "5523622" "5593927" "5604379" "5643830" "5646828" "5677576" "5683942" "5710071" "5715144" "5726489" "5736456" "5741729" "5759047" "5817986" "5844304" "5851911" "5973389" "5984691" "5992012" "5994766" "6025647" "6048753" "6133626" "6147413" "6165815" "6166444" "6169329" "6181010" "6198169" "6204559" "6232666" "6242815" "6255671" "6278177" "6287893" "6316839" "6329608" "6340606" "6426562").PN. OR ("6965160").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 11:50

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S53	33076	semiconductor and package and die	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 12:35
S54	2156	S53 and underfill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 12:35
S55	1180	S54 and encapsulat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 12:36
S56	990	S55 and ("361".clas. "174".clas. "257".clas.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 12:37
S57	3	"6713810".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/02 13:27
S58	0	2002/197891	US-PGPUB	OR	ON	2006/05/02 16:50
S59	0	2002/0197891	US-PGPUB	OR	ON	2006/05/02 16:50